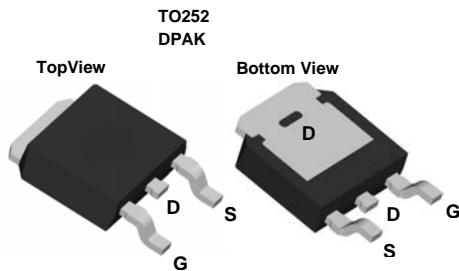


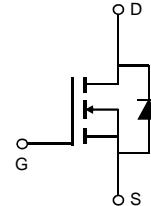
## Features

- 100V, 15A  
 $R_{DS(ON)}$  Typ= 86mΩ @  $V_{GS}$  = 10V  
 $R_{DS(ON)}$  Typ= 96mΩ @  $V_{GS}$  = 4.5V
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge



## Applications

- Load Switch
- PWM Application
- Power Management



## Absolute Maximum Ratings (@ $T_J$ = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units	
$V_{DS}$	Drain-to-Source Voltage	100	V	
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V	
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	15	A
		$T_C = 100^\circ\text{C}$	9	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	60	A	
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	12	mJ	
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	44	W
$R_{θJC}$	Thermal Resistance, Junction to Case		3	
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C	

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{ON})}$	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10\text{V}, I_D = 5\text{A}$	-	86.0	108.0	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 3\text{A}$	-	96.0	125.0	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$	-	1050	-	pF
$C_{\text{oss}}$	Output Capacitance		-	44	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	36	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 50\text{V}, I_D = 2\text{A}$	-	20	-	nC
$Q_{gs}$	Gate Source Charge		-	2.8	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	4	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$ $I_D = 3\text{A}, R_{\text{GEN}} = 1.8\Omega$	-	6	-	ns
$t_r$	Turn-On Rise Time		-	7	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	21	-	ns
$t_f$	Turn-Off Fall Time		-	3	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	15	-	A
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	60	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_s = 10\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F = 10\text{A}, di/dt = 100\text{A/us}$	-	22	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	29	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. EAS condition :  $TJ=25^\circ\text{C}, VDD=50\text{V}, VG=10\text{V}, L=0.5\text{mH}, Rg=25\Omega, IAS=7\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$ .

## Typical Performance Characteristics

Figure 1: Output Characteristics

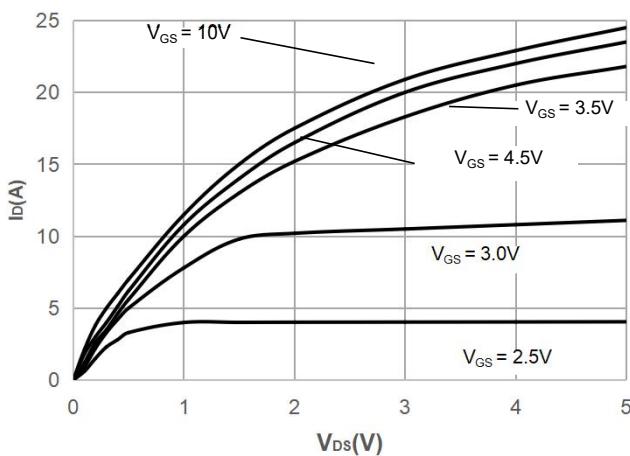


Figure 2: Typical Transfer Characteristics

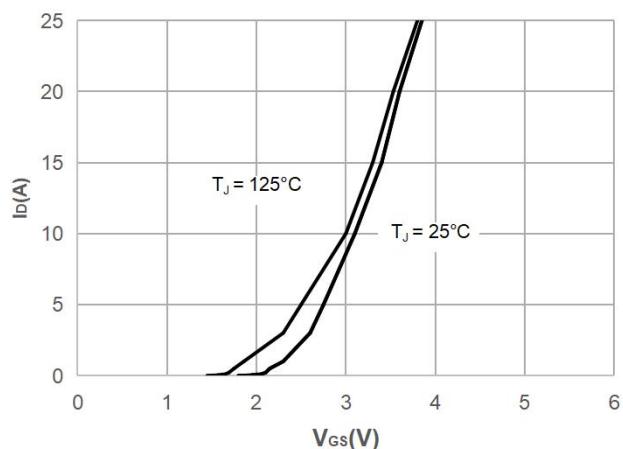


Figure 3: On-resistance vs. Drain Current

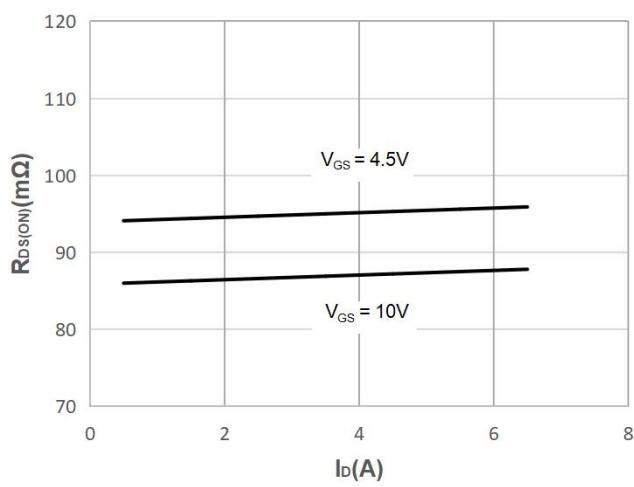


Figure 4: Body Diode Characteristics

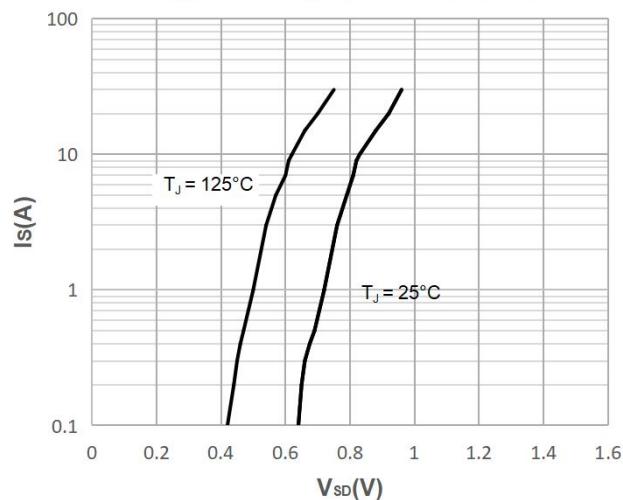


Figure 5: Gate Charge Characteristics

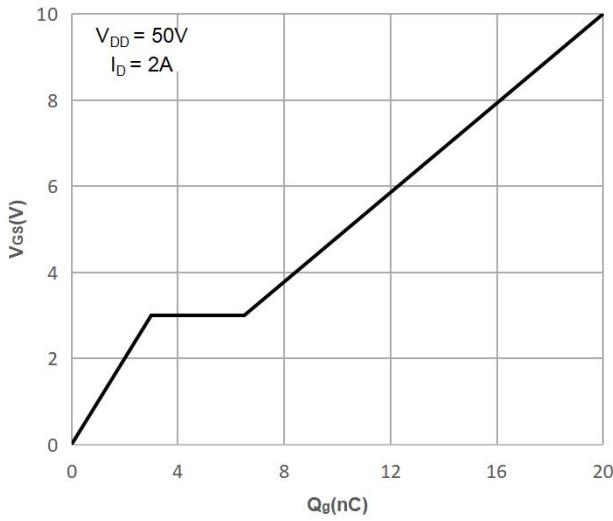
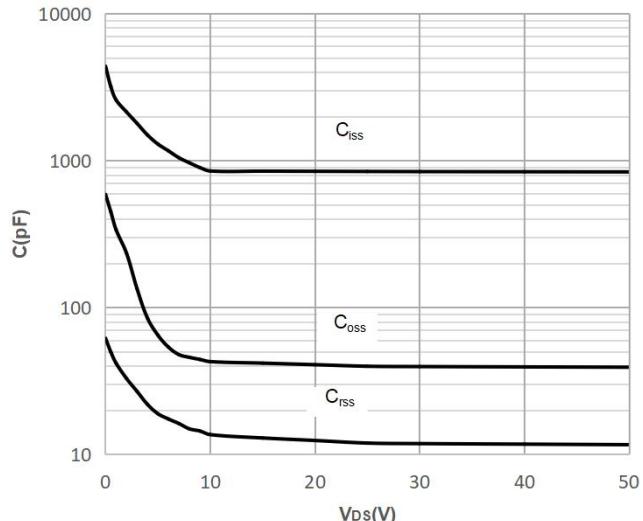


Figure 6: Capacitance Characteristics



## Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

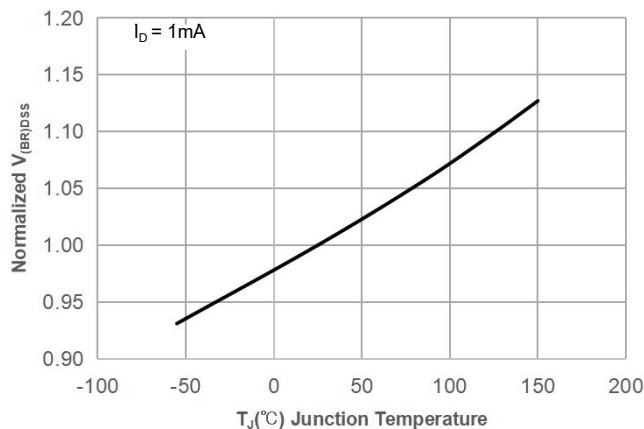


Figure 8: Normalized on Resistance vs. Junction Temperature

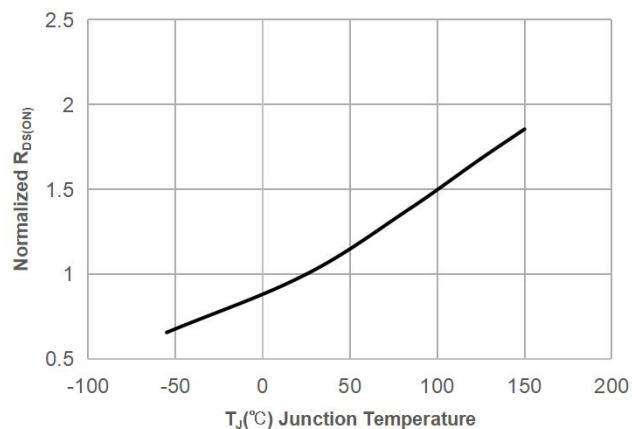


Figure 9: Maximum Safe Operating Area

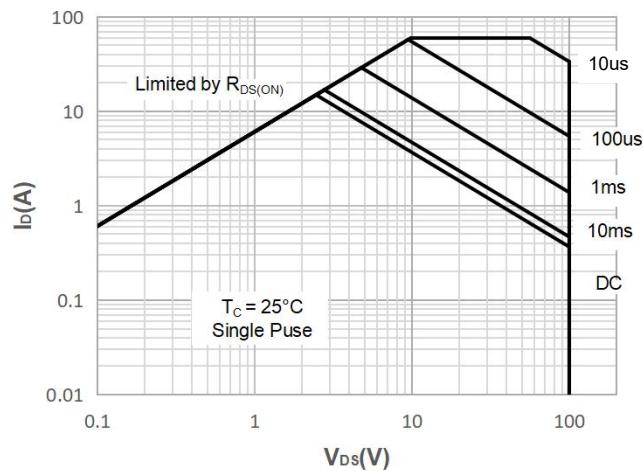


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

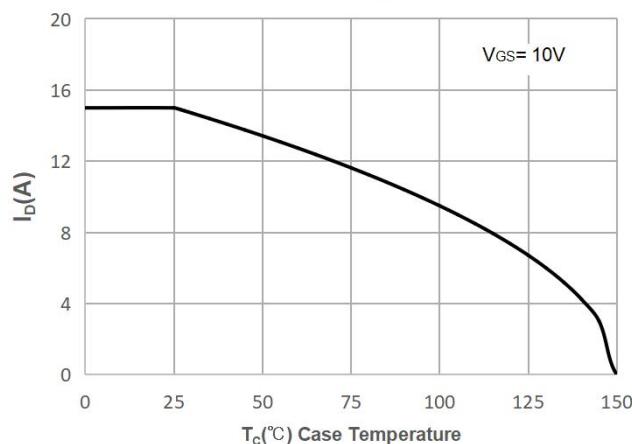


Figure 11: Normalized Maximum Transient Thermal Impedance

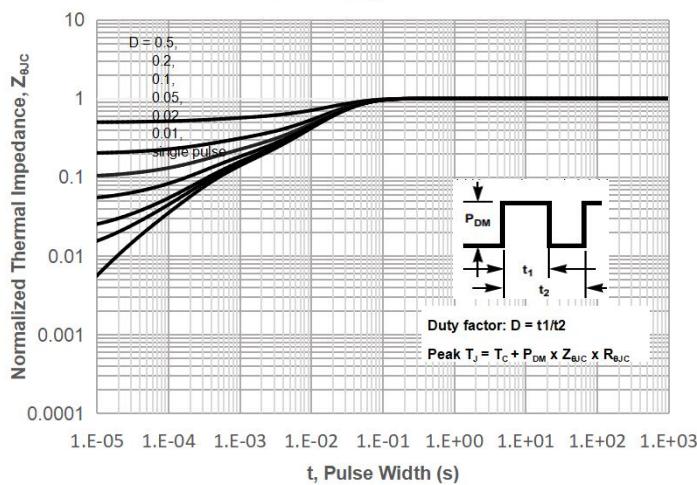
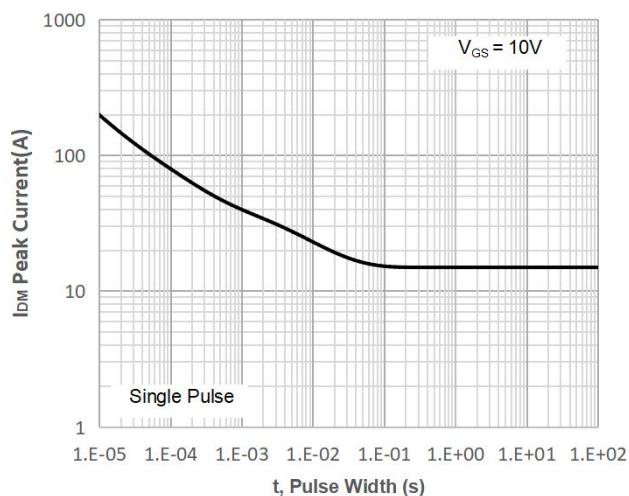


Figure 12: Peak Current Capacity



## Test Circuit

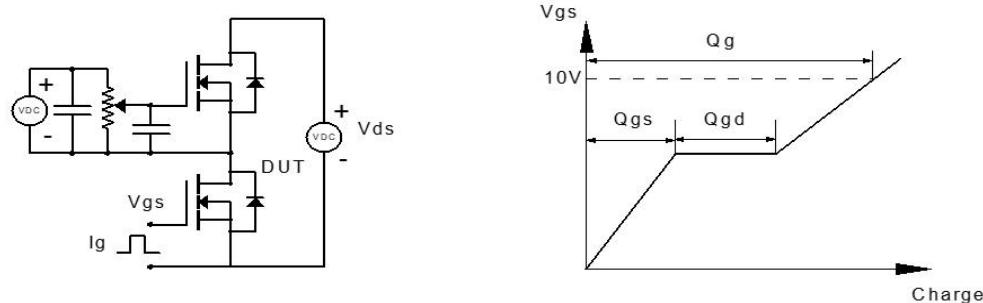


Figure 1: Gate Charge Test Circuit & Waveform

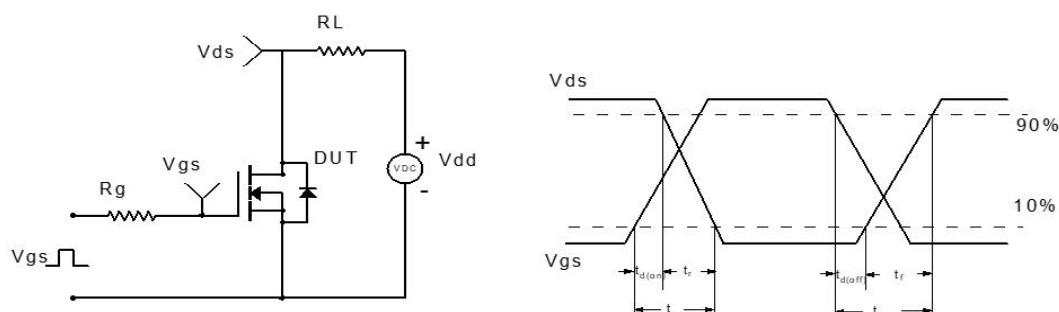


Figure 2: Resistive Switching Test Circuit & Waveform

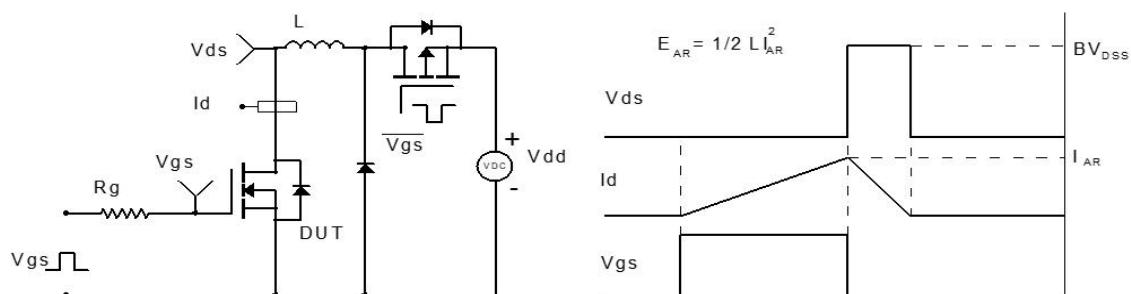


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

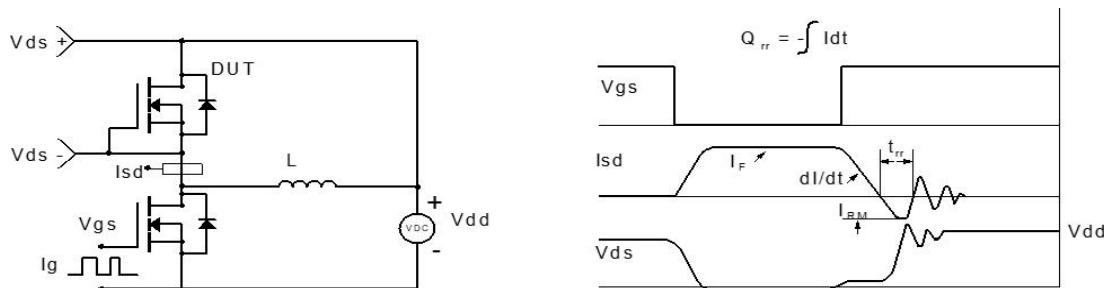
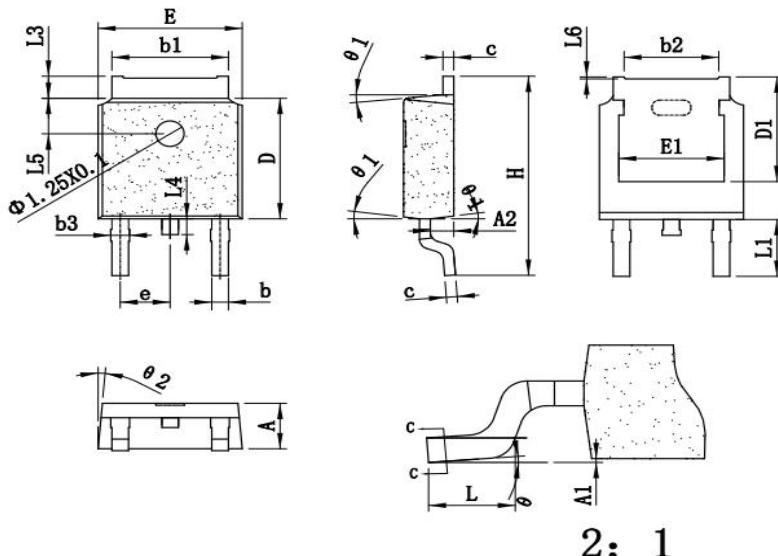


Figure 4: Diode Recovery Test Circuit & Waveform

## Package Mechanical Data(TO-252-3L)



SYMBOL	mm		
	MIN	NOM	MAX
*A	2.20	2.30	2.38
*A1	0.00	—	0.15
*A2	0.90	1.00	1.10
*b	0.72	0.78	0.85
b1	5.23	5.33	5.46
b2	4.05	4.20	4.35
*b3	0.78	0.85	0.90
*c	0.47	0.52	0.55
*D	6.00	6.10	6.20
D1	5.40REF		
*E	6.50	6.60	6.70
E1	4.70	4.83	4.92
*θ	2.286BSC		
*H	9.90	10.10	10.20
*L	1.40	1.55	1.70
L1	2.90REF		
L3	0.90	—	1.20
L4	0.75	0.85	0.95
L5	1.70	1.80	1.90
L6	0.00	0.06	0.12
*θ	0°	—	5°
θ1	5°	7°	9°
θ2	5°	7°	9°